

PART NUMBER 54LS147JB-ROCV

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All re-creations are done with the approval of the Original Component Manufacturer. (OCM)

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceeds the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-38535
 - Class Q Military
 - Class V Space Level

Qualified Suppliers List of Distributors (QSLD)

 Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OCM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.



LS147, LS148

10-Line to 4-Line and 8-Line to 3-Line Priority Encoders

These TTL encoders feature priority decoding of the inputs to ensure that only the highest-order data line is encoded. The '147 and 'LS147 devices encode nine data lines to four-line (8-4-2-1) BCD. The implied decimal zero condition requires no input condition, as zero is encoded when all nine data lines are at a high logic level. The '148 and 'LS148 devices encode eight data lines to three-line (4-2-1) binary (octal). Cascading circuitry (enable input EI and enable output EO) has been provided to allow octal expansion without the need for external circuitry. For all types, data inputs and outputs are active at the low logic level. All inputs are buffered to represent one normalized Series 54/74 or 54/74LS load, respectively

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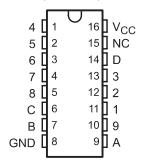
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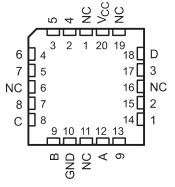
'147, 'LS147

- Encode 10-Line Decimal to 4-Line BCD
- Applications Include:
 - Keyboard Encoding
 - Range Selection

SN54147, SN54LS147 . . . J OR W PACKAGE SN74147, SN74LS147 . . . D OR N PACKAGE (TOP VIEW)



SN54LS147 . . . FK PACKAGE (TOP VIEW)

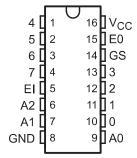


NC - No internal connection

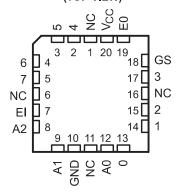
'148, 'LS148

- Encode 8 Data Lines to 3-Line Binary (Octal)
- Applications Include:
 - n-Bit Encoding
 - Code Converters and Generators

SN54148, SN54LS148...J OR W PACKAGE SN74148, SN74LS148...D, N, OR NS PACKAGE (TOP VIEW)



SN54LS148 . . . FK PACKAGE (TOP VIEW)

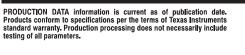


TYPE	TYPICAL DATA DELAY	TYPICAL POWER DISSIPATION
'147	10 ns	225 mW
'148	10 ns	190 mW
'LS147	15 ns	60 mW
'LS148	15 ns	60 mW

NOTE: The SN54147, SN54LS147, SN54148, SN74147, SN74LS147, and SN74148 are obsolete and are no longer supplied.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.





description/ordering information

These TTL encoders feature priority decoding of the inputs to ensure that only the highest-order data line is encoded. The '147 and 'LS147 devices encode nine data lines to four-line (8-4-2-1) BCD. The implied decimal zero condition requires no input condition, as zero is encoded when all nine data lines are at a high logic level. The '148 and 'LS148 devices encode eight data lines to three-line (4-2-1) binary (octal). Cascading circuitry (enable input EI and enable output EO) has been provided to allow octal expansion without the need for external circuitry. For all types, data inputs and outputs are active at the low logic level. All inputs are buffered to represent one normalized Series 54/74 or 54/74LS load, respectively.

ORDERING INFORMATION

TA	PACKAG	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74LS148N	SN74LS148N
200 1 7000	0010 0	Tube	SN74LS148D	1.0440
0°C to 70°C	SOIC - D	Tape and reel	SN74LS148DR	LS148
	SOP - NS	Tape and reel	SN74LS148NSR	74LS148
	CDIP - J	Tube	SNJ54LS148J	SNJ54LS148J
−55°C to 125°C	CFP - W	Tube	SNJ54LS148W	SNJ54LS148W
	LCCC - FK Tube		SNJ54LS148FK	SNJ54LS148FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE - '147, 'LS147

				INPUTS						OUTI	PUTS	
1	2	3	4	5	6	7	8	9	D	С	В	Α
Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н
Х	X	Χ	Χ	Χ	Χ	Χ	X	L	L	Н	Н	L
Х	X	Χ	Χ	Χ	Χ	Χ	L	Н	L	Н	Н	Н
Х	Χ	Χ	Χ	Χ	Χ	L	Н	Н	Н	L	L	L
Х	Χ	Χ	Χ	Χ	L	Н	Н	Н	Н	L	L	Н
Х	Χ	Χ	Χ	L	Н	Н	Н	Н	Н	L	Н	L
Х	Χ	Χ	L	Н	Н	Н	Н	Н	Н	L	Н	Н
Х	Χ	L	Н	Н	Н	Н	Н	Н	Н	Н	L	L
Х	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	L	Н
L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L

H = high logic level, L = low logic level, X = irrelevant

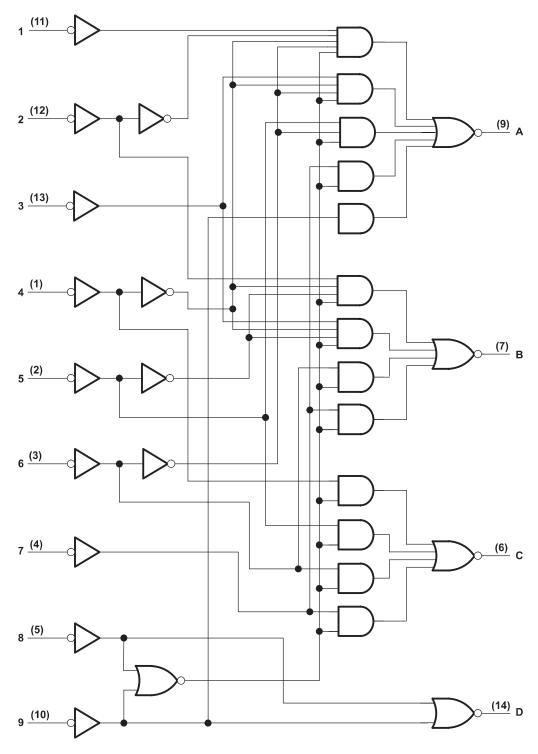
SN54147, SN54148, SN54LS147, SN54LS148 SN74147, SN74148 (TIM9907), SN74LS147, SN74LS148 10-LINE TO 4-LINE AND 8-LINE TO 3-LINE PRIORITY ENCODERS SDLS053B - OCTOBER 1976 - REVISED MAY 2004

FUNCTION TABLE - '148, 'LS148

				INPUTS	}					C	OUTPUT	S	
EI	0	1	2	3	4	5	6	7	A2	A 1	A0	GS	EO
Н	Х	Х	Х	Χ	Х	Χ	Χ	X	Н	Н	Н	Н	Н
L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L
L	Х	X	X	Χ	X	Χ	Χ	L	L	L	L	L	Н
L	Х	X	X	Χ	X	Χ	L	Н	L	L	Н	L	Н
L	Х	Χ	Χ	Χ	Χ	L	Н	Н	L	Н	L	L	Н
L	Х	Χ	Χ	Χ	L	Н	Н	Н	L	Н	Н	L	Н
L	Х	Χ	Χ	L	Н	Н	Н	Н	Н	L	L	L	Н
L	Х	Χ	L	Н	Н	Н	Н	Н	Н	L	Н	L	Н
L	Х	L	Н	Н	Н	Н	Н	Н	Н	Н	L	L	Н
L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L	Н

H = high logic level, L = low logic level, X = irrelevant

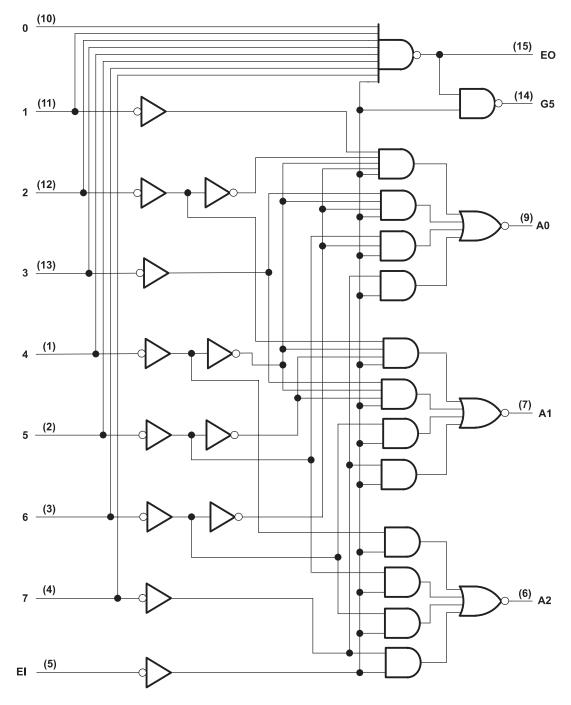
'147, 'LS147 logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.



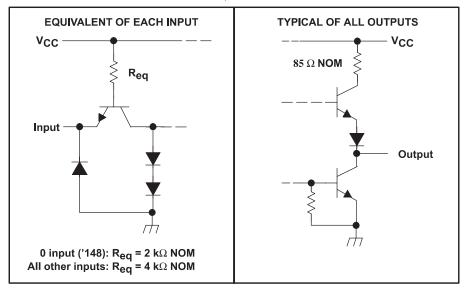
'148, 'LS148 logic diagram (positive logic)



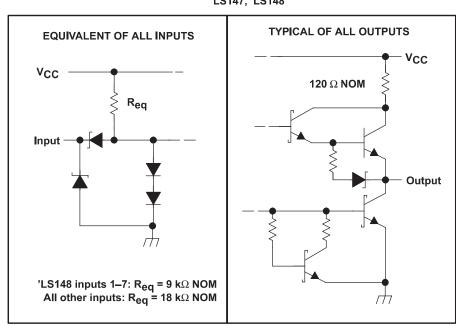
Pin numbers shown are for D, J, N, NS, and W packages.

schematics of inputs and outputs

'147, '148



'LS147, 'LS148



SN54147, SN54148, SN54LS147, SN54LS148 SN74147, SN74148 (TIM9907), SN74LS147, SN74LS148 10-LINE TO 4-LINE AND 8-LINE TO 3-LINE PRIORITY ENCODERS

SDLS053B - OCTOBER 1976 - REVISED MAY 2004

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)		7	'V
Input voltage, V _I : '147, '148		5.5	i V
'LS147, 'LS148		7	'V
Inter-emitter voltage: '148 only (see Note 2) .		5.5	V
Package thermal impedance θ _{JA} (see Note 3)	: D package	73°C/	W'
-	N package	67°C/	W/
	NS package	64°C/	W/
Storage temperature range, T _{stg}		. −65°C to 150°	°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Voltage values, except inter-emitter voltage, are with respect to the network ground terminal.
 - 2. This is the voltage between two emitters of a multiple-emitter transistor. For '148 circuits, this rating applies between any two of the eight data lines, 0 through 7.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			SN54'			SN74'		SN54LS'			SN74LS'			
		MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	4.5	5	5.5	4.75	5	5.25	V
loh	High-level output current		,	-800		,	-800		,	-400		,	-400	μΑ
loL	Low-level output current			16			16			4			8	mA
TA	Operating free-air temperature	-55		125	0		70	-55		125	0		70	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SN54147, SN54148, SN54LS147, SN54LS148 SN74147, SN74148 (TIM9907), SN74LS147, SN74LS148 10-LINE TO 4-LINE AND 8-LINE TO 3-LINE PRIORITY ENCODERS

SDLS053B - OCTOBER 1976 - REVISED MAY 2004

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	D4.D4.44E		TEST 601	unitions.		'147			'148		
	PARAME	IER	I IEST COM	NDITIONS†	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
٧ _{IH}	High-level input vo	oltage			2			2			V
VIL	Low-level input voltage						8.0			8.0	V
٧IK	Input clamp voltag	e	V _{CC} = MIN,	I _I = -12 mA			-1.5			-1.5	V
Vон	High-level output voltage		V _{CC} = MIN, V _{IL} = 0.8 V,	V _{IH} = 2 V, I _{OH} = -800 μA	2.4	3.3		2.4	3.3		٧
VOL	Low-level output voltage		V _{CC} = MIN, V _{IL} = 0.8 V,	V _{IH} = 2 V, I _{OL} = 16 mA		0.2	0.4		0.2	0.4	V
lį	Input current at maximum input voltage		V _{CC} = MIN,	V _I = 5.5 V			1			1	mA
1	High-level input	0 input	V	V- = 2.4.V						40	^
ΊΗ	current	Any input except 0	$V_{CC} = MAX$,	V _I = 2.4 V			40			80	μΑ
	Low-level input	0 input	V MAY	V = 0.4 V						-1.6	Л
ΙL	current	Any input except 0	V _{CC} = MAX,	V _I = 0.4 V			-1.6			-3.2	mA
los	Short-circuit outpu	ıt current§	V _{CC} = MAX	_	-35		-85	-35		-85	mA
loo	Supply ourrent		V _{CC} = MAX	Condition 1		50	70		40	60	mA
Icc	Supply current		(See Note 5)	Condition 2		42	62		35	55	IIIA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 5: For '147, I_{CC} (Condition 1) is measured with input 7 grounded, other inputs and outputs open; I_{CC} (Condition 2) is measured with all inputs and outputs open. For '148, I_{CC} (Condition 1) is measured with inputs 7 and EI grounded, other inputs and outputs open; I_{CC} (Condition 2) is measured with all inputs and outputs open.

SN54147, SN74147 switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	WAVEFORM	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	A.m.,	A	lia mbasa sudand			9	14	
t _{PHL}	Any	Any	In-phase output	C _L = 15 pF,		7	11	ns
^t PLH	Anv	Any	Out of phase output	$R_L = 400 \Omega$		13	19	no
tPHL	Any	Any	Out-of-phase output	·		12	19	ns



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time.

SN54148, SN74148 switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 1)

PARAMETER†	FROM (INPUT)	TO (OUTPUT)	WAVEFORM	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
tpLH	4 7	40.44 40	la abassa saturat			10	15		
t _{PHL}	1–7	A0, A1, or A2	In-phase output			9	14	ns	
t _{PLH}	4 7	40.44 40	0.4.5			13	19		
t _{PHL}	1–7	A0, A1, or A2	Out-of-phase output			12	19	ns	
t _{PLH}	0.7	F0	0.4 -6 -6			6	10		
^t PHL	0–7	EO	Out-of-phase output			14	25	ns	
t _{PLH}	0.7	66	l	$C_L = 15 pF,$		18	30		
t _{PHL}	0–7	GS	In-phase output	$R_L = 400 \Omega$	R _L = 400 Ω		14	25	ns
t _{PLH}	El	AO A1 AO	la abasa suda d			10	15		
^t PHL	EI	A0, A1, or A2	In-phase output			10	15	ns	
t _{PLH}	F.	00	la abassas da d			8	12		
tpHL		El GS In-p	In-phase output			10	15	ns	
tpLH	EI	EO	In-phase output			10	15	20	
t _{PHL}		LO	in-priase output			17	30	ns	

[†] tpLH = propagation delay time, low-to-high-level output. tpHL = propagation delay time, high-to-low-level output.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

					5	N54LS	,	5	N74LS	,	
	PARAME	TER	TEST CON	DITIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIH	High-level input vo	oltage			2			2			V
VIL	Low-level input voltage						0.7			0.8	٧
٧ _{IK}	Input clamp voltage		V _{CC} = MIN,	I _I = −18 mA			-1.5			-1.5	٧
VOH	High-level output	voltage	V _{CC} = MIN, V _{IL} = 0.8 V,	V _{IH} = 2 V, I _{OH} = -400 μA	2.5	3.4		2.7	3.4		V
.,	1 11 1 1		V _{CC} = MIN,	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	V
VOL	Low-level output voltage		V _{IH} = 2 V, V _{IL} = V _{IL} MAX	I _{OL} = 8 mA					0.35	0.5	V
	Input current at	'LS148 inputs 1–7	V MAN				0.2			0.2	
"	maximum input voltage	All other inputs	V _{CC} = MAX,	V _I = 7 V			0.1			0.1	mA
	High-level input	'LS148 inputs 1–7	.,,				40			40	
ΙΉ	current	All other inputs	V _{CC} = MAX,	V _I = 2.7 V			20			20	μΑ
	Low-level input	'LS148 inputs 1–7	.,				-0.8			-0.8	
IIL	current	All other inputs	V _{CC} = MAX,	V _I = 0.4 V			-0.4			-0.4	mA
Ios	Short-circuit outpu	ıt current§	V _{CC} = MAX		-20		-100	-20		-100	mA
loo	Supply current		V _{CC} = MAX	Condition 1		12	20		12	20	mA
Icc	Supply current		1 12 7 7 1 1 1 1 1	Condition 2		10	17		10	17	IIIA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 6: For 'LS147, I_{CC} (Condition 1) is measured with input 7 grounded, other inputs and outputs open; I_{CC} (Condition 2) is measured with all inputs and outputs open. For 'LS148, I_{CC} (Condition 1) is measured with inputs 7 and EI grounded, other inputs and outputs open; I_{CC} (Condition 2) is measured with all inputs and outputs open.



[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[§] Not more than one output should be shorted at a time.

SN54147, SN54148, SN54LS147, SN54LS148 SN74147, SN74148 (TIM9907), SN74LS147, SN74LS148 10-LINE TO 4-LINE AND 8-LINE TO 3-LINE PRIORITY ENCODERS SDLS053B - OCTOBER 1976 - REVISED MAY 2004

SN54LS147, SN74LS147 switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	WAVEFORM	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	A	A	la abasa satura			12	18	
^t PHL	Any	Any	In-phase output	C _L = 15 pF,		12	18	ns
^t PLH	Any	Δ m) (Out-of-phase output	$R_L = 2 k\Omega$		21	33	no
t _{PHL}		Any				15	23	ns

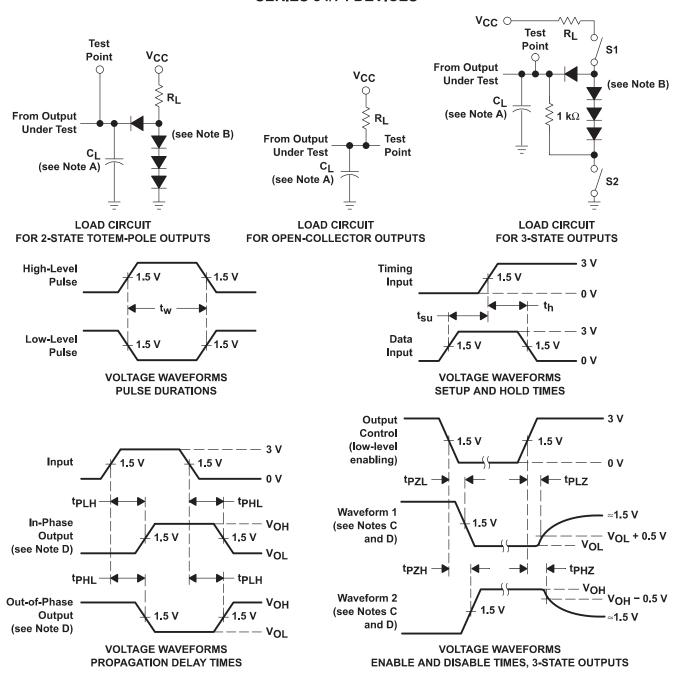
SN54LS148, SN74LS148 switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 2)

PARAMETER†	FROM (INPUT)	TO (OUTPUT)	WAVEFORM	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	1–7	AO A4 ~ AO	la alaca autout			14	18	
^t PHL	1-7	A0, A1, or A2	In-phase output			15	25	ns
^t PLH	4.7	00 01 00 00	Out of phase submut			20	36	
t _{PHL}	1–7	A0, A1, or A2	Out-of-phase output			16	29	ns
^t PLH	0.7		Out of phase subsut			7	18	
t _{PHL}	0–7	EO	Out-of-phase output			25	40	ns
t _{PLH}	0.7	00	l	C _L = 15 pF,		35	55	
^t PHL	0–7	GS	In-phase output	$R_L = 2 k\Omega$		9	21	ns
t _{PLH}	F.	AO A4 AO	la abasa sudaud	1		16	25	
t _{PHL}	EI	A0, A1, or A2	In-phase output			12	25	ns
t _{PLH}	F1	00	la alasa a ada d			12	17	
t _{PHL}	EI		In-phase output			14	36	ns
^t PLH	EI		In phase output			12	21	ns
t _{PHL}		20	In-phase output			23	35	115

[†] tpLH = propagation delay time, low-to-high-level output tpHL = propagation delay time, high-to-low-level output



PARAMETER MEASUREMENT INFORMATION **SERIES 54/74 DEVICES**

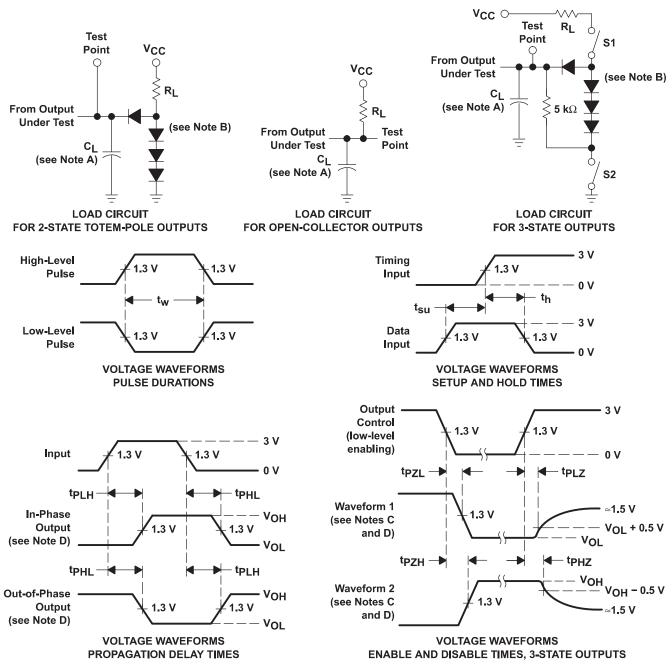


- NOTES: A. C_I includes probe and jig capacitance.
 - B. All diodes are 1N3064 or equivalent.
 - C. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - D. S1 and S2 are closed for tpLH, tpHL, tpHZ, and tpLZ; S1 is open, and S2 is closed for tpZH; S1 is closed, and S2 is open for tpZL.
 - E. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_{\Omega} \approx 50 \Omega$; t_r and $t_f \leq$ 7 ns for Series 54/74 devices and t_r and $t_f \le 2.5$ ns for Series 54S/74S devices.
 - F. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION **SERIES 54LS/74LS DEVICES**



- NOTES: A. C_I includes probe and jig capacitance.
 - B. All diodes are 1N3064 or equivalent.
 - C. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - D. S1 and S2 are closed for tpl H, tpHL, tpHZ, and tpl Z; S1 is open, and S2 is closed for tpZH; S1 is closed, and S2 is open for tpZI.
 - E. Phase relationships between inputs and outputs have been chosen arbitrarily for these examples.
 - F. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O \approx 50~\Omega$, $t_f \leq$ 1.5 ns, $t_f \leq$ 2.6 ns.
 - G. The outputs are measured one at a time, with one input transition per measurement.

Figure 2. Load Circuits and Voltage Waveforms



APPLICATION INFORMATION

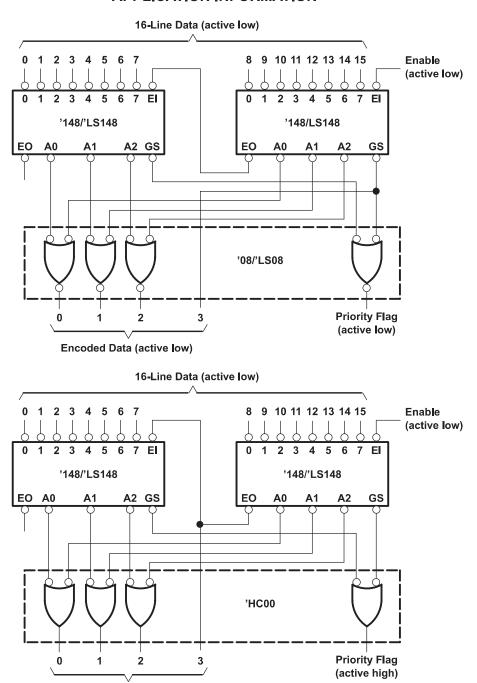


Figure 3. Priority Encoder for 16 Bits

Encoded Data (active high)

Because the '147/'LS147 and '148/'LS148 devices are combinational logic circuits, wrong addresses can appear during input transients. Moreover, for the '148/'LS148 devices, a change from high to low at El can cause a transient low on GS when all inputs are high. This must be considered when strobing the outputs.



24-Aug-2018

PACKAGING INFORMATION

Device Marking	(4/5)	78027012A SNJ54LS 148FK	7802701EA SNJ54LS148J	7802701FA SNJ54LS148W	JM38510/ 36001B2A	JM38510/ 36001BEA	JM38510/ 36001BFA	JM38510/ 36001B2A	JM38510/ 36001BEA	JM38510/ 36001BFA	SN54LS148J	LS148	LS148	SN74LS148N	74LS148	78027012A SNJ54LS 148FK	7802701EA SNJ54LS148J
Op Temp (°C)		-55 to 125	-55 to 125	-55 to 125	-55 to 125	-55 to 125	-55 to 125	-55 to 125	-55 to 125	-55 to 125	-55 to 125	0 to 70	0 to 70	0 to 70	0 to 70	-55 to 125	-55 to 125
MSL Peak Temp	(3)	N / A for Pkg Type	N / A for Pkg Type	N / A for Pkg Type	N / A for Pkg Type	N / A for Pkg Type	N / A for Pkg Type	N / A for Pkg Type	N / A for Pkg Type	N / A for Pkg Type	N / A for Pkg Type	Level-1-260C-UNLIM	Level-1-260C-UNLIM	N / A for Pkg Type	Level-1-260C-UNLIM	N / A for Pkg Type	N / A for Pkg Type
Lead/Ball Finish	(9)	POST-PLATE	A42	A42	POST-PLATE	A42	A42	POST-PLATE	A42	A42	A42	CU NIPDAU	CU NIPDAU	CU NIPDAU	CU NIPDAU	POST-PLATE	A42
Eco Plan	(2)	ТВО	TBD	TBD	TBD	TBD	TBD	TBD	TBD	TBD	TBD	Green (RoHS & no Sb/Br)	TBD	ТВО			
Pins Package	Qty	-	1	1	-	1	1	1	1	-	1	40	2500	25	2000	_	-
		50	16	16	20	16	16	20	16	16	16	16	16	16	16	20	16
Package	Drawing	Ŧ	ſ	W	퐀	ſ	M	FK	ſ	>	ſ	D	D	z	NS	Я	٦
Package Type Package		CCC	CDIP	CFP	CCCC	CDIP	CFP	CCCC	CDIP	CFP	CDIP	SOIC	SOIC	PDIP	SO	TCCC	CDIP
Status	(1)	ACTIVE	ACTIVE	ACTIVE	ACTIVE	ACTIVE	ACTIVE	ACTIVE	ACTIVE	ACTIVE	ACTIVE	ACTIVE	ACTIVE	ACTIVE	ACTIVE	ACTIVE	ACTIVE
Orderable Device		78027012A	7802701EA	7802701FA	JM38510/36001B2A	JM38510/36001BEA	JM38510/36001BFA	M38510/36001B2A	M38510/36001BEA	M38510/36001BFA	SN54LS148J	SN74LS148D	SN74LS148DR	SN74LS148N	SN74LS148NSR	SNJ54LS148FK	SNJ54LS148J

24-Aug-2018



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Device Marking SNJ54LS148W 7802701FA Op Temp (°C) -55 to 125 N / A for Pkg Type MSL Peak Temp Lead/Ball Finish A42 Eco Plan TBD Pins Package ģ 16 Package Drawing ≥ Package Type CFP ACTIVE Status Orderable Device SNJ54LS148W

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design. PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based lame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width

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OTHER QUALIFIED VERSIONS OF SN54LS148, SN74LS148:

Catalog: SN74LS148

24-Aug-2018

Military: SN54LS148

NOTE: Qualified Version Definitions:

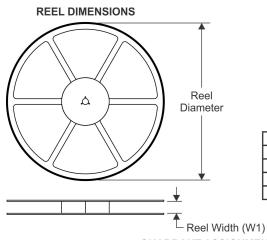
Catalog - TI's standard catalog product

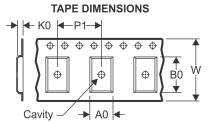
Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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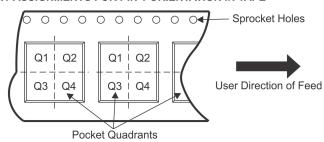
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	3
	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

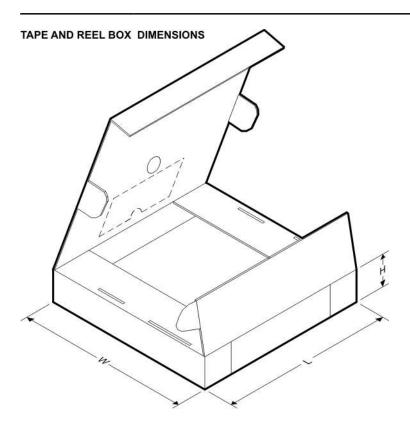


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS148DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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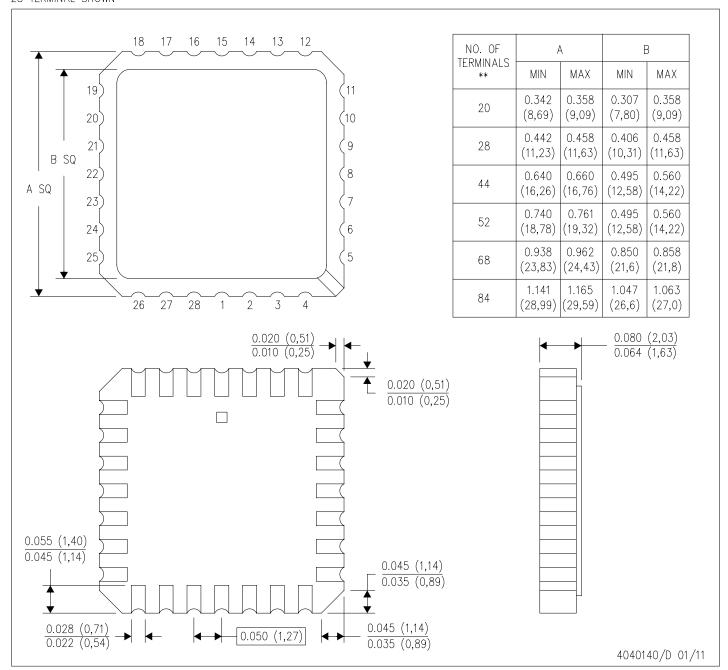
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74LS148DR	SOIC	D	16	2500	333.2	345.9	28.6	

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

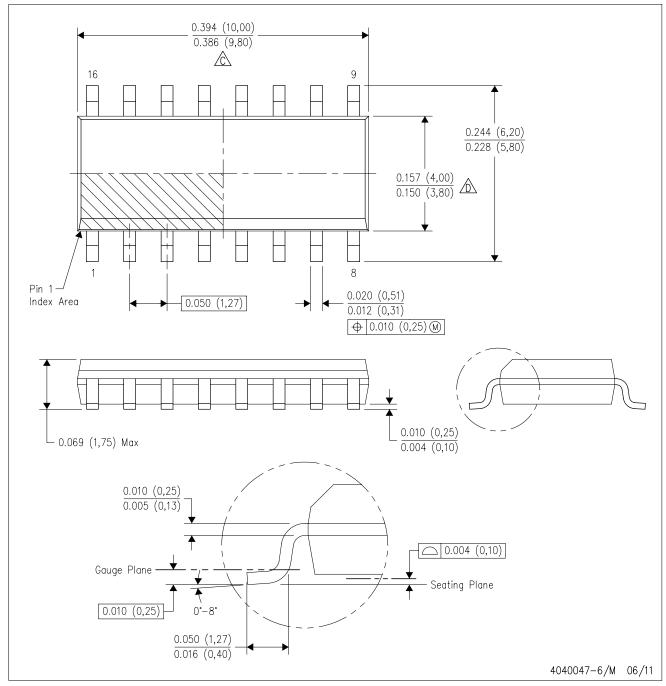


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE

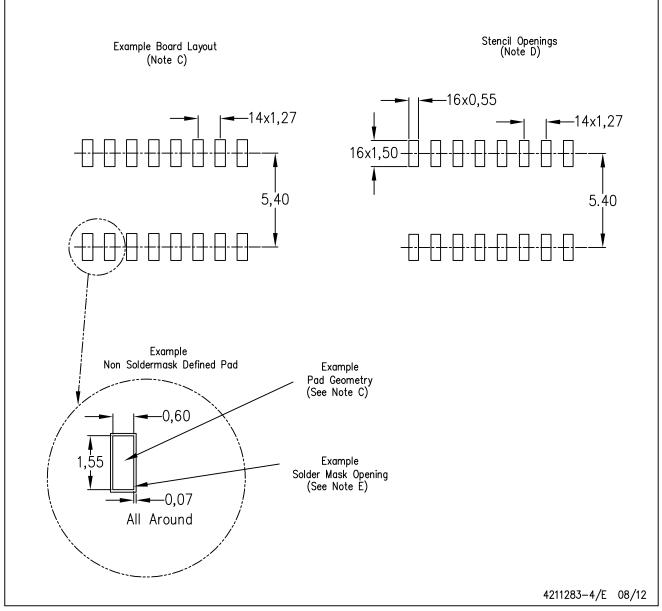


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

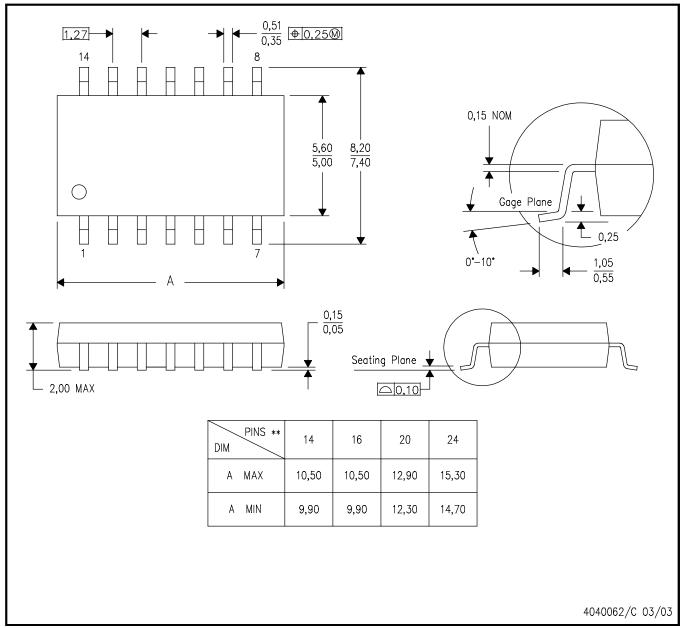


MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

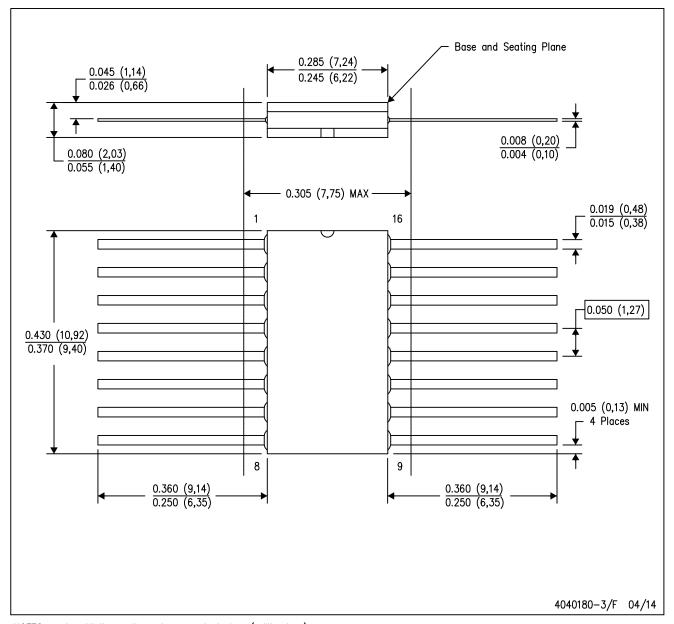


- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



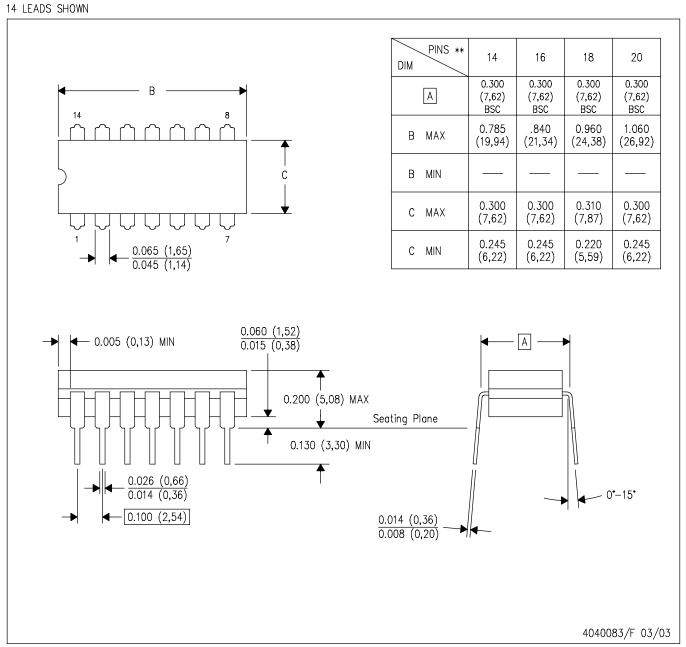
W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



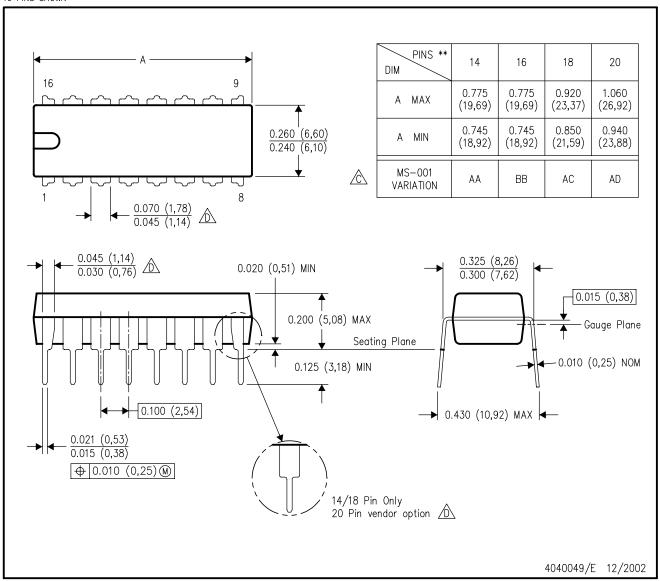


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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